



博來科技股份有限公司

LEX COMPUTECH CO.,LTD.

Lex SYSTEM[®]

Product
Roadmap

LEX believes your success will be our success.

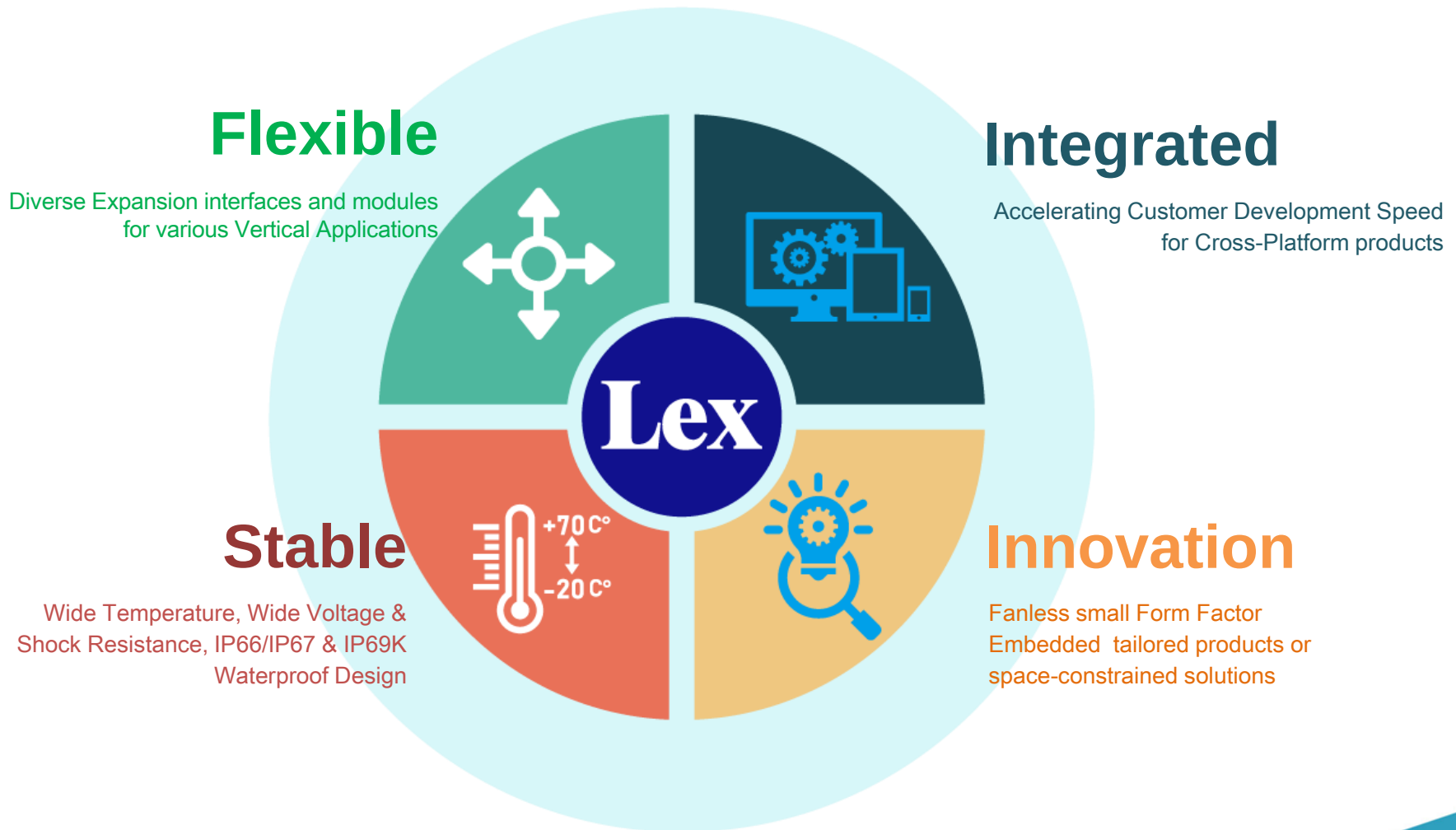


2026 Q3

Contents

- LEX System Features & Advantages
- Embedded Solution Overview
- Embedded Solution Case Study
- Product Highlights
- Product Development Timeline
- Product long term supply
- Contact Information

Features & Advantages



LEX SYSTEM – Embedded Solution

LEX offers design and manufacturing of industrial motherboards, industrial computers, expansion boards, and customized industrial computers, including edge computing systems and AI intelligent application platforms. Our in-house developed products cover four major categories:



1 Embedded IPC Board

- Single Board Computer
- CPU board
- Computer On Module
- UPS board
- ARM-based SBC



2 Customized Motherboard & Chassis

Innovating Research & Integration Services for
Global OEM/ODM and System Integrators

• Applications



AI / Visual Analytics



Smart Manufacturing /
Machine Vision



IoT / IIoT



Smart Healthcare/
AI Medical Imaging



Smart Transportation &
Railways



Maritime Shipping
& Navigation



Defense / Military
Robust Computers



Edge Computing
Edge Gateway Control



Networking/
Communication Equipment

LEX SYSTEM – Embedded Solution



3

Fanless Rugged Panel PC,
Fanless Embedded Systems, Servers



4

Expansion Boards/Cards &
Related Accessories

Fanless Rugged Panel PC



•SUPER series (7"/10.1"/10.4"/15")



•VITA series (10.1"/15"/21.5"/23.8")



•Slim series (8.4"/10.2"/15.1"/17")



•SHARK IP66/67 **waterproof** (10.1"/13.3")



•STAR IP66/67 **waterproof** (10.4"/12.1"/15.1")



•**Stainless** IP66/IP67/IP69K **waterproof**

(10.4"/15.1"/19")

Fanless Embedded System



•Rugged /Waterproof System



•In-vehicle System

•DIN Rail System



•1U server

•AI image Analysis & Machine Vision

•Ultra Compact / Compact System

•High-Speed Ethernet Network Card / PoE / Fiber Card

•4G / 5G / WiFi / Bluetooth Module

•Video Capture Card

•USB / SIM / COM / Display Conversion Card

•M.2 / eIO Expansion Card

•Storage Card

•Digital IO Card

•Carriers and Converter Boards

•Power Boards and Charger Modules

Embedded Solution— Case Study

Smart Transportation



Robotics



Smart Manufacturing



Smart Healthcare



2026 Q3 Product Highlights

3I160DW-3.5" SBC



Intel® Core™ Ultra CPU
(Panther Lake)
2 x HDMI®, LVDS or eDP (BIOS), 1 X Type C
2 x DDR5 SODIMM Max 96 GB
5 x Intel 2.5 GbE, 3 x USB 3.2, 5 x USB 2.0
3 x M.2, 1 x Nano SIM, 1 x PCIe x2, 2 x PCIe x4
HD Audio, 3 x MIPI-CSI, 4 x COM, 4DI / 4DO

2I140D-2.5" SBC



Intel® Core™ Ultra CPU
(Meteor Lake-U/H) (Arrow Lake-U/H)
HDMI®, eDP, 2 x MIPI-CSI
Onboard LPDDR5 16 / 32GB
4 x Intel 2.5 GbE, 3 x USB 3.2, 4 x USB 2.0
2 x M.2, 1 x Nano SIM, 2 x COM, 4DI / 4DO

3I140HW-3.5" SBC



Intel® Core™ Ultra CPU
(Meteor Lake-U/H) (Arrow Lake-U/H)
DP, HDMI®, LVDS or eDP (BIOS)
2 x DDR5 SODIMM Max 64GB
3 x Intel 2.5 GbE, 4 x USB 3.2, 3 x USB 2.0
3 x M.2, 1 x Nano SIM, HD Audio
4 x COM, 4DI / 4DO, 2 X MIPI-CSI

2I132DW-2.5" SBC



Intel® 13th Gen Raptor Lake-U CPU
Onboard LPDDR5, 16 / 32GB
HDMI®, eDP
4 x Intel 2.5 GbE, 3 x USB 3.2
4 x USB 2.0, 2 x COM, 4DI / 4DO,
2 x M.2, 1 x Nano SIM

2I740DW-2.5" SBC



Intel® ATOM Amston Lake x7000 CPU
Onboard LPDDR5, Max 32GB
1 x HDMI®
3 x Intel 2.5 GbE, 3 x USB 3.2, 2 x USB 2.0
2 x M.2, 2 x COM

2I740AW-2.5" SBC



Intel® ATOM Amston Lake x7000 CPU
Onboard LPDDR5, Max 32GB
HDMI®, 1 x USB 3.2 Type C DP ALT,
1 x Intel 2.5 GbE, 4 x COM
4 x USB 3.2, 1 x USB 2.0
2 x M.2, 1 x Nano SIM,

2I740CW-2.5" SBC



Intel® ATOM Amston Lake x7000 CPU
1 x SODIMM DDR5, Max 16GB
HDMI®, Type C, LVDS or eDP (BIOS)
2 x Intel 2.5 GbE, 3 x USB 3.2, 2 x USB 2.0
1 x USB 3.2 Type C, 2 x M.2, 1 x Nano SIM
2 x MIPI-CSI, 4 x COM, 4DI/4DO

2I642DW-2.5" SBC



Intel® ATOM
Elkhart Lake x6413E / J6412 CPU
Onboard LPDDR5, 16 / 32GB
2 x HDMI®, eDP 3 x Intel 2.5 GbE
2 x USB 3.0, 3 x USB 2.0
2 x M.2, 1 x Nano SIM,

Product Highlights (Embedded IPC Board)



2I130HW-2.5" Plus SBC
2I130DW-2.5" Plus SBC
2I132DW-2.5" Plus SBC
3I130DW-3.5" Plus SBC
3I130TW-161x150 mm SBC



2I110D-2.5" Plus SBC
2I110AW-2.5" Plus SBC
3I110HW/BW-3.5" Plus SBC



3I470DW-155 x150 mm SBC



CI370D-217 x 185 mm SBC
CI371D-217 x 223 mm SBC
3I370DW-155 x130 mm SBC



2I810D-2.5" Plus SBC
3I810DW-3.5" Plus SBC
3I810HW/BW-3.5" Plus SBC



2I640PW-Compute on Module
2I640HL-2.5" Plus SBC with Hailo-8
2I640DW-2.5" Plus SBC
2I642DW-2.5" Plus SBC
2I640CW-2.5" Plus SBC
2I640HW-2.5" Plus SBC
2I640SW-2.5" Plus SBC
3I640DW-3.5" SBC
3I640CW-3.5" SBC



2NOR01- 2.5" Plus carrier board
For Board for Edge AI solution with
NVIDIA® Jetson Orin™ Nano (Super)NX

ORIN-TW

Carrier Board for Railway solution with
NVIDIA® Jetson Orin™ Nano(Super) / NX

2NOR02- compact carrier board
For Edge AI solution with NVIDIA® Jetson
Orin™ Nano / NX

2NOR03- compact carrier board
For Edge AI solution with NVIDIA® Jetson
Orin™ Nano / NX



2N8MP01- 2.5" Plus SBC

NXP-HAI02- -carrier board with Hailo AI chip
For Edge AI solution with I.MX8M Plus CPU

NXP-HAI03 -carrier board with Hailo AI chip
For Edge AI solution with I.MX8M Plus CPU

2026 Q3 Product Development timeline



Intel® Core™ Ultra CPU (Series 3)



3I160DW

Intel® Core™ Ultra 300 Series (Panther Lake) processors

Revamped I GPU and integrated NPU

2 x DDR5 SODIMM, Max 128GB

Multiple Independent display: 2 x HDMI®, ®, LVDS or eDP (BIOS), 1 x Type C DP ALT

5 x Intel 2.5 GbE LAN, 3 x USB 3.2 Gen1x1, 5 x USB 2.0,

1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM,

1 x PCIe x2, 2 x PCIe x4

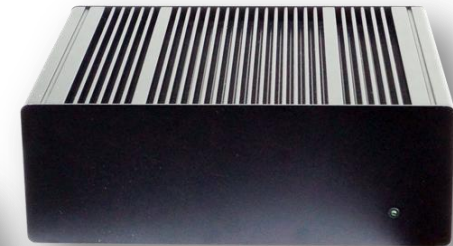
4 x COM, 4DI / 4DO, 3 x MIPI-CSI, HD Audio

TPM 2.0, SMBus, I2C, I2S

Dimension: 146 x 150 mm



HAWK 3I160DW



2026 Q3 Product Development timeline



Rock 2i140D

2i140D

Intel® Core™ Ultra 7/5 Series processors
(Meteor Lake –U/H & Arrow Lake-U/H)
On board LPDDR5 16/32 GB
1 x HDMI®, eDP, 4 x Intel 2.5 GbE LAN,
3 x USB 3.2 Gen 1, 4 x USB 2.0
1 x M.2 M Key, 1 x M.2 B Key, 1 x Nano SIM
2 x COM, 4DI / 4DO, Audio (OEM)
2 x MIPI-CSI, SMBus, I2C, DC IN+ 12V
Dimension: 113 x 112 mm

Intel® Core™ Ultra CPU



3i140DW

Intel® Core™ Ultra 7/5 Series processors
(Meteor Lake –U/H & Arrow Lake-U/H)
2 x DDR5 SODIMM, Max 64GB
1 x HDMI®, 1 x DP, LVDS or eDP (BIOS)
1 x Type C DP ALT Mode
5 x Intel 2.5 GbE LAN, 3 x USB 3.2 Gen 1, 3 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, 1 x PCIe
4 x COM, 2 x CANBus, 4DI / 4DO, Audio
TPM 2.0, SMBus, I2C, I2S, Wide Range DC IN+9~36V
Dimension: 150 x 155 mm



HAWK 3i140DW



3i140HW

Intel® Core™ Ultra 7/5 Series processors
(Meteor Lake –U/H & Arrow Lake-U/H)
2 x DDR5 SODIMM, Max 64GB
1 x HDMI®, LVDS or eDP (BIOS)
1 x Type C DP ALT Mode
3 x Intel 2.5 GbE LAN, 4 x USB 3.2 Gen 1, 3 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, High Speed Connector (PCIe x2)
4 x COM, 2 x MIPI-CSI, 4DI / 4DO, Audio
TPM 2.0, SMBus, I2C, Wide Range DC IN+9~36V
Dimension: 146 x 150 mm



SealPro 3 3i140HW



HAWK 3i140HW+ 8 CH GMSL

2026 Q3 Product Development timeline



Intel® Core™ Ultra CPU



CI870CW

Intel® Core™ Ultra 7/5 (Arrow Lake-S) Series processors
2 x DDR5 SODIMM, Max 96 GB
Multiple Independent display:
1 x HDMI®, 1 x DP, 1 x LVDS or eDP (BIOS), 1 x Type C DP ALT
5 x Intel 2.5 GbE LAN, 4 x USB 3.2 Gen 1, 4 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, 1 x PCIe x16
10 x COM, 8DI / 8DO, Audio
TPM 2.0, SMBus, I2C, I2S
Wide Range DC IN+12~36V
Dimension: LEX form factor (186 x 217 mm)



CI870AW

Intel® Core™ Ultra 7/5 (Arrow Lake-S) Series processors
2 x DDR5 SODIMM, Max 96GB
Multiple Independent display:
1 x HDMI®, 1 x DP, 1 x Type C DP ALT
2 x Intel 2.5 GbE LAN, 4 x USB 3.2 Gen 1, 4 x USB 2.0
1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, 1 x PCIe x16
4 x COM, 8DI / 8DO, TPM 2.0, SMBus, I2C, I2S
Wide Range DC IN+12~36V
Dimension: LEX form factor (186 x 217 mm)



TWISTER(L)-CI870AW



TWISTER(L)-CI870CW



1U Fanless-CI870AW



1U Fanless-CI870CW

2026 Q3 Product Development timeline



13th Gen Intel® Core™ Raptor Lake-P/U



21130HW

Intel® 13th Gen Raptor Lake-U/P CPU
1 x DDR5 SODIMM (Max. 32GB)
HDMI®, eDP, LVDS
2 x Intel 2.5 GbE, 4 x USB 3.2
4 x USB 2.0, 2 x COM, 4DI / 4DO,
HD Audio, 1 x Mini PCIe, 1 x M.2
108 x 102 mm



ROCK 21130HW



SealPro 21130HW



21130DW / 21132DW



Intel® 13th Gen Raptor Lake-U CPU
1 x DDR5 SODIMM (Max. 32GB) -21130DW
Onboard LPDDR5 16/ 32GB-21132DW
HDMI®, eDP
4 x Intel 2.5 GbE, 3 x USB 3.2
4 x USB 2.0, 2 x COM, 4DI / 4DO,
2 x M.2, 1 x Nano SIM
108 x 102/ 108 x 105 mm



FOX 21130DW



SKY 2 21130DW



ROCK 21130DW



31130DW

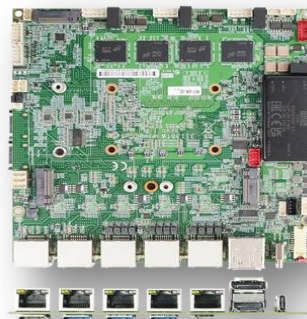
Intel® 13th Gen Raptor Lake-P / U CPU
2 x DDR5 SODIMM (Max. 64GB)
2 x HDMI®, eDP, 1 x Type C DP ALT Mode
5 x Intel 2.5 GbE, 3 x USB 3.2, 5 x USB 2.0
1 x Mini PCIe, 2 x M.2, 1 x Nano SIM
2 x COM, 4DI / 4DO
146 x 110 mm



HAWK 31130DW



SKY 3 31130DW



31130TW

Intel® 13th Gen Raptor Lake- U CPU
On-board LPDDR5 (16GB/32 GB)
HDMI®, DP, eDP, 5 x Intel 2.5 GbE,
3 x USB 3.2, 3 x USB 2.0, 3 x M.2,
1 x Nano SIM, 2 x ISO-COM, HD Audio
2 x ISO- CANBus, 4DI / 4DO, onboard NVMe
CPC -Ignition Delay on/off control
161 x 150 mm



HAWK 31130TW (M12)



Mobile Rack (Optional)

2026 Q3 Product Development timeline

NVIDIA Jetson Orin Nano(Super)/ NX SOM Carrier Board

JETSON
Orin™ NX

JETSON
Orin™ Nano



CPU Board:

NVIDIA Jetson NX: 8 / 16GB LPDDR5, 70 / 100 TOPs

NVIDIA Jetson Nano(Super): 4 / 8GB LPDDR5, 20 / 40 TOPs

AI Accelerator: NVIDIA® Jetson Orin™ Nano(Super) / Orin™ NX

2NOR02

1 x HDMI®, 1 x GbE
8 x USB 3.1, 1 x Type C USB 3.1 / 2.0 (OTG), 1 x USB 2.0
1 x RS232 (OEM to RS422)
1 x M.2 M key, 1 x M.2 B key, URAT, I2S, 2 x I2C



FOX 2NOR02

2NOR03

1 x HDMI®, 1 x GbE, 1 x 2.5GbE
2 x USB 3.1, 1 x Type C USB 3.1 / 2.0 (OTG)
1 x RS232 (OEM Option RS422)
1 x M.2 M key, 1 x M.2 B key
Support **8 X GMSL cameras**



FOX 2NOR03+GM04

ORIN-TW

1 x DP, 5 x GbE (1 + 4 x PoE)
1 x USB 3.1 Type C ; 2 x USB 3.1 Type A ; 1x USB 2.0
Mic-in / Line-out ; AMP 2W, 2 x SATA
2 x Isolated RS232 / RS422 / RS485, 1 x Isolated CANBus
1 x M.2 M key, 4 x M.2 B key, 1 x M.2 E Key, 1 x Nano SIM
2 x MIPI CSI, SPI, I2S, 3 x I2C, 8DI / 8 DO,
ISO Wide Range +9~36V, CPC-Ignition on/off delay control



HAWK ORIN-TW
M12 I/O / Mobile Rack (Optional)

2NOR01

1 x HDMI®, 2 x 2.5GbE, 1 x GbE
4 x USB 3.1, 1 x Type C USB 3.1 / 2.0 (OTG), 1 x USB 2.0
Mic-in / Line-out ; AMP 2W
2 x RS232 (Option RS422), 1 x CANBus
1 x M.2 M key 2 x M.2 B key, 1 x SIM, 4DI / 4DO
Internal wafer: SPI, I2S, I2C, USB 2.0



SKY 2NOR01



ROCK 2NOR01

2026 Q3 Product Development timeline



NXP i.MX8M Plus /ARM Cortex-A53



2N8MP01

NXP i.MX8M Plus (Quad core)
ARM Cortex A53 + M7 CPU
LPDDR4, 4GB / 8GB
Independent display: 1 x HDMI®, LVDS,
3 x GbE LAN, 2 x USB 3.0, 3 x USB 2.0
2 x COM, 3 x M.2, 1 x Nano SIM, 1 x Type C USB 3.0 (OTG)
4DI / 4DO, 1 x MIPI (CSI), 1 x CANBus
115.4 x 84.5 mm



NET-II 2N8MP01



PALM-NEX001

NXP i.MX8M Plus (Quad core)
ARM Cortex A53 CPU
LPDDR4, 8GB (NEX-8MP)
32GB eMMC 5.1 (NEX-8MP),
expandable to 256GB
HDMI®; 2 x GbE; 2 x USB 3.0 / 2.0
1 x Micro SD, 1 x RS232, 1 x RS485
DC input : +5V
71.4W x 71.4D x 29.5H mm

**Ultra Compact solution
with Onboard Hailo-8™ AI processor**



NXP-HAI02 / HAI03

NXP i.MX8M Plus (Quad core) ARM Cortex-A53 CPU
LPDDR4, 8GB (NEX-8MP), 32-256GB eMMC 5.1 (NEX-8MP)
Mini HDMI®, 1 x USB 3.0 Type C, 1 x GbE (M12) or 2 x RJ45;
1 x USB 3.0 Type A, 1 x Micro SD,
M8 Connector: DC Power, LAN, DI/DO, RS485
Wide Range DC-IN +9-24V
Dimension: 66W x 94D x 30.8H mm



NXP-HAI02



NXP-HAI03

With NEX-8MP computer on module



MINI NXP-HAI02



MINI NXP-HAI03

2026 Q3 Product Development timeline



Intel® Amston Lake ATOM x7000 series processor



2I740DW

Intel® ATOM Amston Lake x7000 series CPU
Onboard LPDDR5, Max 32GB
HDMI®, 3 x Intel 2.5 GbE,
3 x USB 3.2, 2 x USB 2.0
2 x M.2, 1 x Nano SIM, 2 x COM,
Wide Range DC-IN +9~24V
115.4 x 84.5 mm



2I740CW

Intel® ATOM Amston Lake x7000 series CPU
1 x DDR5 SODIMM, Max. 16GB
HDMI®, Type C ALT, 1 x LVDS or eDP (BIOS)
2 x Intel 2.5 GbE, 3 x USB 3.2, 2 x USB 2.0
1 x USB3.2 Type C, 2 x MIPI-CSI, 4DI/4DO
2 x M.2, 4 x COM, Wide Range DC-IN +9~36V
108 x 102 mm



2I740AW

Intel® ATOM Amston Lake x7000 series CPU
Onboard LPDDR5, Max 32GB
eMMC 5.1 32GB ~ 256GB
HDMI®, 1 x USB 3.2 Type C DP ALT,
1 x Intel 2.5 GbE, 4 x USB 3.2, 1 x USB 2.0
2 x M.2, 1 x Nano SIM, 4 x COM,
Wide Range DC-IN +9~24V
117 x 98.2 mm



NET-II 2I740DW



FOX 2I740DW



FOX 2I740CW
FOX 2I740CW



LEX Series Panel PC



TERA 2I740AW
Front



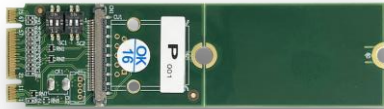
TERA 2I740AW

2026 Q3 Product Development timeline

Expansion Card and Modules

Easy Expansion:

Connect the set to the SBC's M.2 B+M slot to enable 4 x GbE LAN / 4 x PoE LAN / 4 x Fiber Lan / 4 x USB 3.0 and 4 x M.2 + 4 x Micro SIM expansion



CN073 / CN075

M.2 B+M Key 2242 / 2280 to USB 3.0 / PCIe converter board



CU006

1 x USB convert to 4 x USB 3.0 HUB



CL210A

4 Port GbE LAN board



CL210P

4 Port PoE GbE LAN



CL210F

4 Port Fiber LAN board



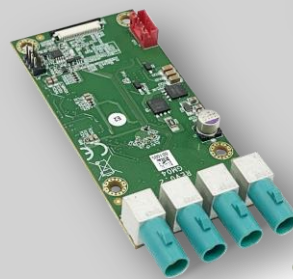
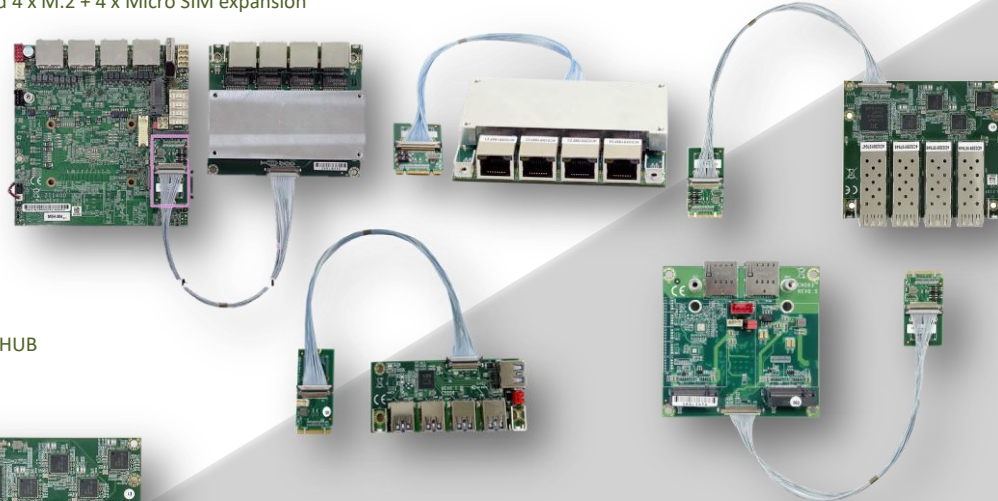
Top



Bottom

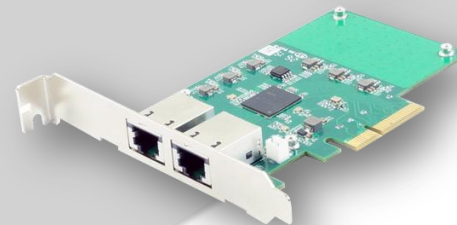
CN063

4 x M.2 + 4 x Micro SIM



GM04

4 CH GMSL input (MIPI-CSI)



E610A

2 x 10 GbE LAN – PCIe Card



ADC002

Analog I/O Board

LEX SYSTEM with Long-Term Supply

EOL Timeline	2026	2027	2028	2030	2031	2032	2033	2034	2035	2036
Bay Trail		Q4								
Apollo Lake	Q4									
Elkhart Lake					Q1					
Amston Lake								Q2		
Skylake 6 th	Q2									
Kaby Lake 7 th	Q2									
Coffee Lake 8 th			Q3							
Coffee Lake 9 th			Q3							
Whisky Lake			Q3							
Comet Lake				Q2						
Tiger Lake UP3				Q3						
Raptor Lake							Q1			
Meteor Lake-U/H							Q4			
Arrow Lake-U				Q1						
Arrow Lake-S				Q1						
Panther Lake										Q1
Nova Lake										Q1
i.MAX 8M Plus									Q1	
Jetson Orin Nano NX				Q1						

* Product life span in alignment with Intel's IOTG / NVIDIA modules Life cycle /NXP CPU longevity.

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